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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/876,396	06/07/2001	Syuuichi Kariyazaki	14701	7345
23389	7590 10/18/2005		EXAMINER	
	OTT MURPHY & PRE	OWENS, DO	OUGLAS W	
SUITE 300			ART UNIT	PAPER NUMBER
GARDEN CIT	Y, NY 11530		2811	

DATE MAILED: 10/18/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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<u> </u>	Application No.	Applicant(s)			
	09/876,396	KARIYAZAKI, SYUUICHI			
Office Action Summary	Examiner	Art Unit			
	Douglas W. Owens	2811			
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the	correspondence address			
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DATE - Extensions of time may be available under the provisions of 37 CFR 1.1: after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period versiliure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be ting will apply and will expire SIX (6) MONTHS from the cause the application to become ABANDONE	N. mely filed the mailing date of this communication. ED (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on <u>06 O</u>	ctober 2003.				
<u></u>	action is non-final.				
3) Since this application is in condition for allowar	3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is				
closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims					
4) ⊠ Claim(s) 1-11 is/are pending in the application 4a) Of the above claim(s) is/are withdray 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-11 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and/or	wn from consideration.				
Application Papers					
9) ☐ The specification is objected to by the Examine	er.				
10) The drawing(s) filed on is/are: a) □ accepted or b) □ objected to by the Examiner.					
Applicant may not request that any objection to the					
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex					
Priority under 35 U.S.C. § 119	•				
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Burea * See the attached detailed Office action for a list	s have been received. Is have been received in Applications In the second secon	tion No red in this National Stage			
Attachment(s)					
1) Notice of References Cited (PTO-892)	4) Interview Summan				
Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	Paper No(s)/Mail D 5) Notice of Informal 6) Other:	Date Patent Application (PTO-152)			

DETAILED ACTION

Claim Objections

1. Claims 4, 5, 8 and 11 are objected to because of the following informalities:

In line 2 of claim 4, "cell" should be replaced with --cells--, and "includes" should be replaced with --include--.

In line 2 of claim 5, "cell" should be replaced with --cells-- and "includes" should be replaced with --include--.

In line 4 of claim 8, "the" should be replaced with --an--.

In lines 3 and 5 of claim 11, --group of-- should be inserted between "first" and "I/O", and "second" and "I/O" respectively.

Appropriate correction is required.

Claim Rejections - 35 USC § 112

- 2. The following is a quotation of the second paragraph of 35 U.S.C. 112:
 - The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.
- 3. Claims 1 11 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
- 4. Claim 1 recites the limitation "the semiconductor chip" in lines 6 and 7. There is insufficient antecedent basis for this limitation in the claim.
- 5. Claim 2 requires that the semiconductor member be a semiconductor chip. The scope of the claim is vague, since it is not known if this is in addition to the

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semiconductor chip mentioned in claim 1 or if the semiconductor member is a second semiconductor chip.

- 6. Claim 3 requires that the mounting member is a package for mounting a semiconductor chip. The scope the claim is vague since it is not known if the semiconductor chip is the chip mentioned in claim 1 or for mounting a second semiconductor chip.
- 7. Claim 1 requires that the electrode terminals be electrically **and mechanically** (emphasis added) connected to the interconnect pads on the semiconductor member. Claim 3 requires that the electrode terminals be disposed on a bottom surface of the packaging substrate. The scope of the claim is vague since it is not understood how the electrode terminals can be mechanically connected to the semiconductor member, which is mounted on the mounting member, when the electrode terminals are on the bottom surface of the substrate. It is further not known if the electrode terminals are on the mounting member, as required in claim 1, or the packaging substrate, as required in claim 3.
- 8. The scope of claim 6 is vague since it is not possible to determine if there is an interconnect line or multiple interconnect lines. It is also unknown if the interconnect line/lines is/are connected to one or multiple interconnect pads. Claim 7 has the same problem
- 9. Claim 7 recites the limitation "the substrate" in line 2. There is insufficient antecedent basis for this limitation in the claim. The claim further requires that the

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substrate includes the interconnect pads. Are the same interconnect pads that are on the semiconductor member (claim 1) also on the substrate?

Claim Rejections - 35 USC § 102

10. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 11. Claims 1, 2 are rejected under 35 U.S.C. 102(e) as being anticipated by US Patent No. 6,225,694 to Terui.

Regarding claim 1, Terui teaches a semiconductor device (Figs. 1 and 2A, for example) comprising:

a semiconductor member (12) having thereon a plurality of interconnect pads (13); and

a mounting member (1) having a plurality of electrode terminals (10) electrically and mechanically connected to the respective interconnect pads for mounting the semiconductor member on the mounting member;

the electrode terminals forming a plurality of I/O cells each having part of the electrode terminals, the I/O cells forming a first group of the I/O cells and a second group of I/O cells disposed on an inner position of the mounting member with respect to the first group.

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Regarding claim 2, Terui teaches a semiconductor device, wherein the semiconductor member is a semiconductor chip, the electrode terminals are internal electrodes disposed on a bottom surface of the semiconductor chip, and the mounting member is a package substrate used for packaging thereon the semiconductor chip.

Regarding claim 6, Terui teaches a semiconductor device, wherein interconnect lines (3) are electrically connected to the interconnect pad and formed in a single interconnect layer.

Response to Arguments

12. Applicant's arguments with respect to claims 1 – 11 have been considered but are most in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Douglas W. Owens whose telephone number is 571-272-1662. The examiner can normally be reached on Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Steven H. Loke can be reached on 571-272-1657. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should

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you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Douglas W Owens

Dougla K. Owers

Examiner Art Unit 2811

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